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**Aehr Test Systems Receives Follow-on Orders Exceeding \$1.3 Million  
for FOX-1™ WaferPak™ Contactors**

**Fremont, CA (August 9, 2017) - Aehr Test Systems (NASDAQ: AEHR)**, a worldwide supplier of semiconductor test and burn-in equipment, today announced it has received follow-on orders exceeding \$1.3 million for multiple WaferPak contactors for its FOX-1 wafer level test system.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, “We are pleased to receive follow-on orders from this customer reflecting additional capacity needs. It’s gratifying to see renewed demand for our proprietary WaferPak contactors from our installed base of FOX-1 systems, as we have seen a lull in purchasing WaferPaks for these older systems. We have been seeing utilization rates increase on our FOX-1 single wafer and FOX-15™ multi-wafer systems, which now join the high utilization rates we have previously reported on our package level test and burn-in system installed base. As our FOX system installed base increases, we expect that our WaferPak full wafer contactors and DiePak® carriers will continue to grow as a percentage of our total sales, particularly with our new FOX-XP™ multi wafer and singulated die/module test and burn-in system.”

The FOX-1 test system is a member of Aehr Test's first generation of volume production full wafer test and burn-in systems and was the first system to be able to test an entire wafer of flash memory or micro-controller devices in parallel using Built-in Self-Test (BIST) techniques. A cost-effective solution for single touchdown full wafer testing, the FOX-1 system is capable of delivering over 12,000 individual device power supplies and tests thousands of devices on a single wafer. It is capable of testing up to 6,000 NOR or NAND flash memories on a 300mm wafer in a single contact using Aehr Test’s integration of BIST and low pin count test methodologies. Aehr Test’s WaferPak contactors can be configured with up to 50,000 contacts or more, resulting in a very low cost of test/ownership.

Aehr Test began volume deliveries of its next generation FOX-1P™ single wafer test system last year. The FOX-1P system is capable of providing up to 16,000 Universal Channel resources (software selectable I/Os, Clocks, Device Power Supplies, or Per-pin Precision Measurement Units) to a single wafer. Both the FOX-1 and FOX-1P systems have the highest number of tester resources per wafer of any product in the market.

Aehr Test’s proprietary WaferPak contactors are available for the FOX-1, FOX-15, and the new FOX-XP multi-wafer test and burn in systems, and are consumables that are uniquely designed to the customers’ devices.

### **About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS and FOX-P™ families of test and burn-in systems and FOX WaferPak™ Aligner, FOX-XP WaferPak Contactor, and FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak Contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System's website at [www.aehr.com](http://www.aehr.com).

### **Safe Harbor Statement**

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak contactor technologies, acceptance by customers of the FOX-XP system, WaferPak Aligner and WaferPak contactors shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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